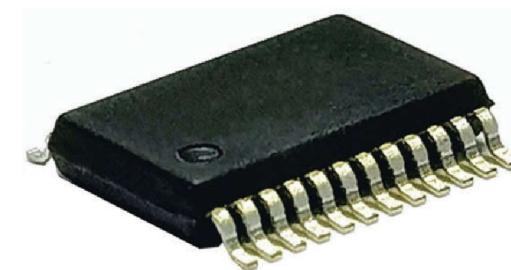



SYMBOL	MILLIMETER		
	MIN	NOM	MAX
A	-	-	1.85
A1	0.05	0.15	0.25
A2	1.40	1.50	1.60
b	0.29	-	0.37
b1	0.28	0.30	0.33
c	0.15	-	0.19
c1	0.14	0.15	0.16
D	8.10	8.20	8.30
Df	8.20	-	8.70
E	7.60	7.80	8.00
E1	5.20	5.30	5.40
e	0.65 BSC		
L	0.65	0.90	1.15
L1	1.15	1.25	1.35
θ	0	-	8°
f	0.05	-	0.20

Note:

1. All dimension are in mm.
2. Dim D & E1 does not include plastic flash;
Df includes plastic flash(f);
Flash: Plastic residual around body edge after
dejunk/singulation.
3. Dim b does not include dambar protrusion/intrusion.
4. Plating thickness 0.007mm-0.015mm



拟制		复审	
审核		会签	
		标准化	
		批准	
制图		批准	
幅面: A4		比例: 1:1	

更改标记	更改内容	签名	日期
 Vinka Microelectronics			
VKXHSSOP24-0.65V11_POD 产品外形图名称		图号: VKXHSSOP24-0.65V11_POD	
单位 mm		版本 V1.1	密级
第1张		共1张	

